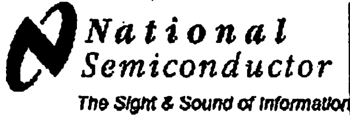
Attn: Dan @ Sierra - Layouts. LMC6041 NSC LMC6061 NSC



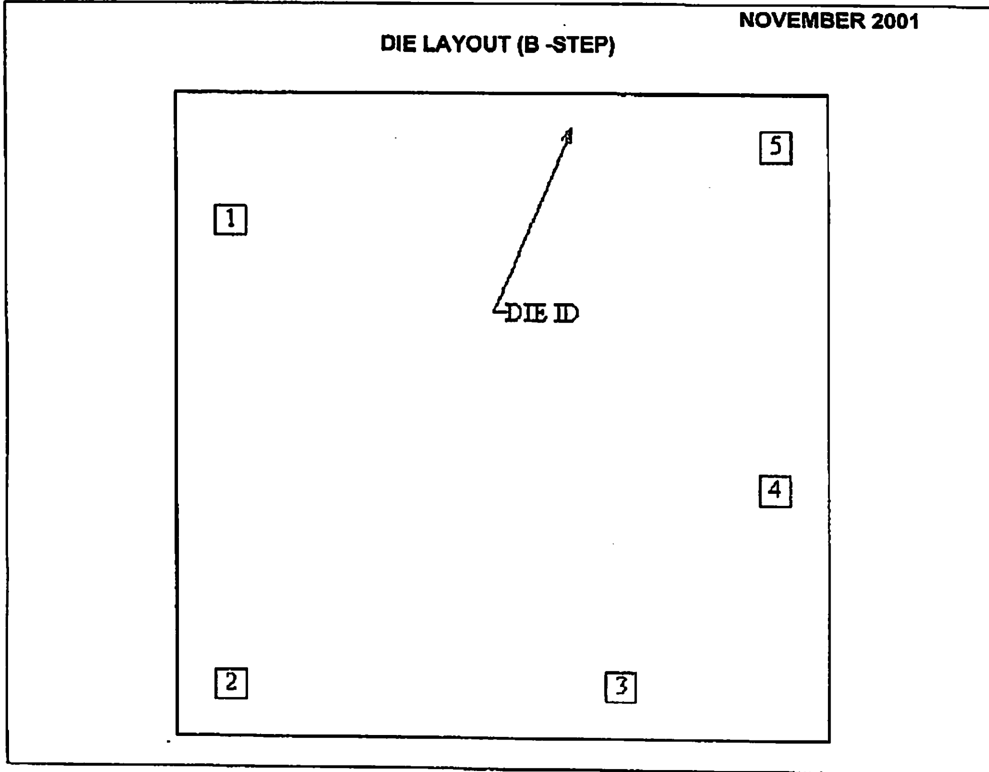
DPBU
Die Datasheet

Best Regards Sharon.

LMC6041 MDC MWC PRELIMINARY
CMOS SINGLE MICROPOWER OPERATIONAL AMPLIFIER

NOVEMBER 2001

DIE LAYOUT (B -STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMC6041B	Bond Pad Opening Size (min)	88µm x 88µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1905µm x 1905µm 75mils x 75mils	Back Side Bias	Floating
Thickness	406µm Nominal		
Min Pitch	742µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

Die Bond Pad Coordinate Locations (B -Step)
(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
INPUT -	1	-800	577	88	x	88
INPUT +	2	-800	-800	88	x	88
V-	3	345	-800	88	x	88
OUTPUT	4	796	-210	88	x	88
V+	5	800	800	88	x	88